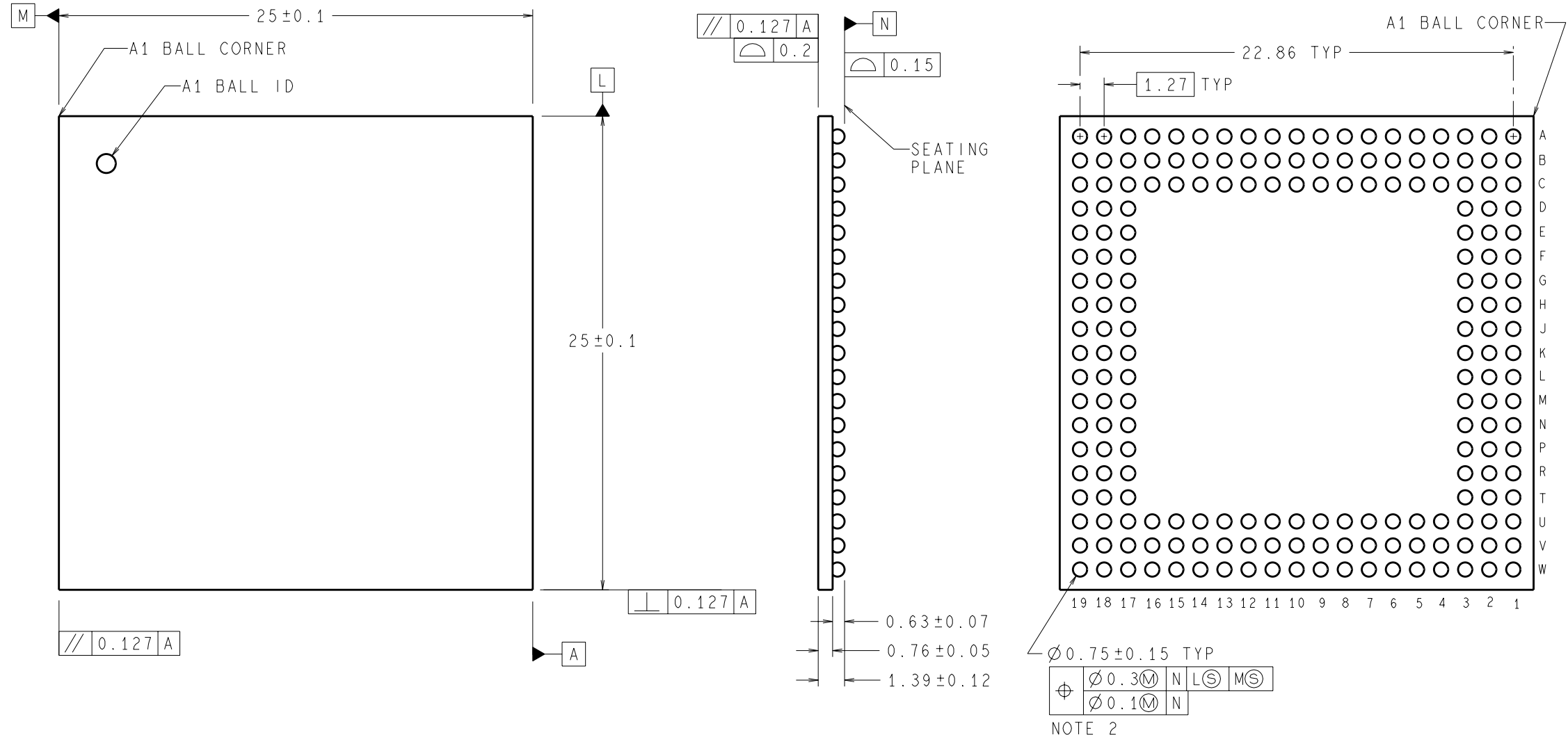


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12384	02/29/2000	TL/MJL



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
 - DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
 - REFERENCE JEDEC REGISTRATION MO-192, VARIATION BAV-1, DATED SEP 1996.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN T. LEQUANG	02/29/2000			
DFTG. CHK. MARTA SUCHY	02/29/2000			
ENGR. CHK. M. J. LEE	02/29/2000	SBGA, 25 X 25 X 1.39 mm, 192 BALL, 1.27 mm PITCH		
 INCH [MM]				
SCALE	SIZE	DRAWING NUMBER	REV	
N/A	C	(SC)MKT-UHA192A	A	
FORMERLY: N/A		SHEET 1 of 1		